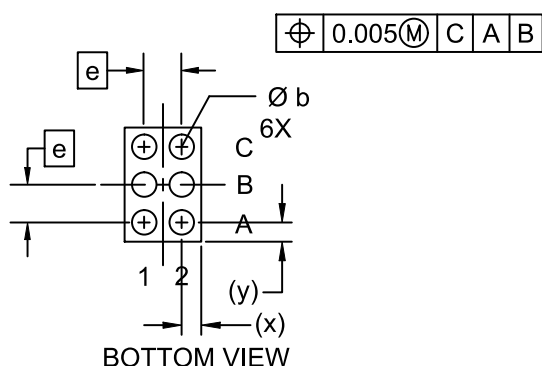
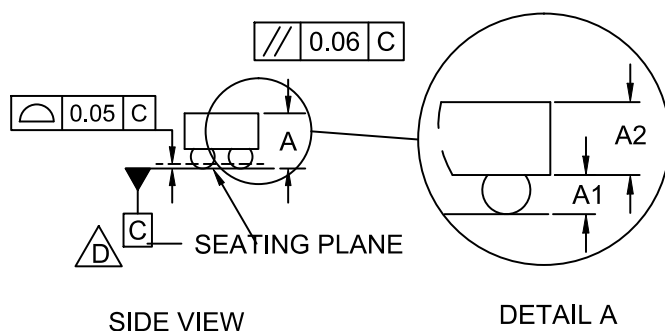
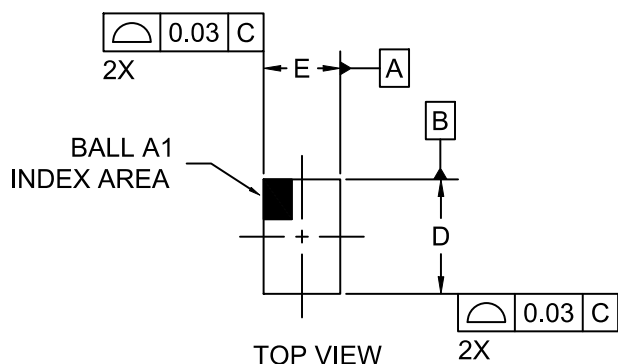


WLCSP6 1.3x0.9x0.574
CASE 567UV
ISSUE O

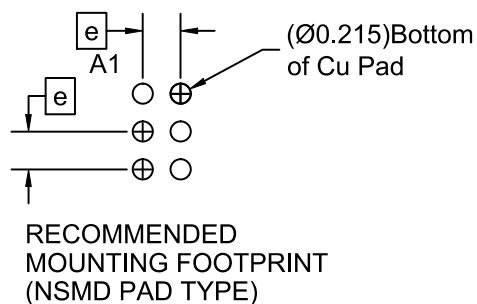
DATE 05 JUL 2017



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.536	0.574	0.612
A1	0.176	0.196	0.216
A2	0.360	0.378	0.396
b	0.240	0.260	0.280
D	1.270	1.300	1.330
E	0.870	0.900	0.930
e	0.40 BSC		
x	0.235	0.250	0.265
y	0.235	0.250	0.265



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